

List of Patents and Publications For Applicant's Information Disclosure Statement  (Use several sheets if necessary)	AMDI:132\HON	10/676,904
	<b>APPLICANT</b> James F. Buller et al.	<b>CERTIFICATE OF MAILING 37 C.F.R. 1.8</b>  I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on the date below: <div style="display: flex; justify-content: space-between;"> <div> Date <u>January 2, 2004</u> </div> <div> <u>Timothy M. Honeycutt</u>  Timothy M. Honeycutt </div> </div>
	<b>FILING DATE</b> October 1, 2003	<b>GROUP</b> 2823

### U.S. PATENT DOCUMENTS


EXAM INIT.	REF. DES.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
WP	A1	6,074,906	June 13, 2000	Jon Cheek et al.	<del>438</del>	<del>231</del>	
WP	A2	US 6,506,642 B1	January 14, 2003	Scott Luning et al.	<del>438</del>	<del>231</del>	

### FOREIGN PATENT DOCUMENTS

EXAM INIT.	REF. DES.	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION

### OTHER ART

EXAM INIT.	REF. DES.	AUTHOR; TITLE; JOURNAL; VOLUME; DATE; PERTINENT PAGES
WP	A3	Dallas Semiconductor; <i>Compensating for Ideality Factor and Series Resistance Differences between Thermal Sense Diodes</i> ; <a href="http://www.maxim-ic.com/an1057">www.maxim-ic.com/an1057</a> ; April 17, 2002; pp. 1-2
WP	A4	Intel; <i>Intel Pentium® III Processor, Thermal Diode</i> ; <a href="http://support.intel.com/support/processors/pentiumiii/sb/CS-007590.htm">http://support.intel.com/support/processors/pentiumiii/sb/CS-007590.htm</a> ; August 12, 2003; pp. 1-3

<b>EXAMINER</b> 	<b>DATE CONSIDERED</b> <u>04/04/05</u>
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Information Disclosure Statement--PTO-1449 (Modified)